

CLAIMS

1. (Deleted)

5 2. (Amended) An anisotropically conductive connector
for electrically connecting the circuit board for
inspection to a wafer by being arranged on the surface of
the circuit board for inspection for conducting electrical
inspection of each of a plurality of integrated circuits
10 formed on the wafer in a state of the wafer, which
comprises:

a frame plate, in which a plurality of
anisotropically conductive film-arranging holes each
extending in a thickness-wise direction of the frame plate
15 have been formed correspondingly to electrode regions, in
which electrodes to be inspected have been arranged, in all
or part of the integrated circuits formed on the wafer,
which is an object of inspection, and a plurality of
elastic anisotropically conductive films arranged in the
20 respective anisotropically conductive film-arranging holes
in this frame plate and each supported by the peripheral
edge about the anisotropically conductive film-arranging
hole,

wherein each of the elastic anisotropically
25 conductive films is composed of a functional part having a
plurality of conductive parts for connection containing
conductive particles exhibiting magnetism at a high density

and extending in the thickness-wise direction of the film,
and arranged correspondingly to the electrodes to be
inspected in the integrated circuits formed on the wafer,
which is the object of inspection, and an insulating part
5 mutually insulating these conductive parts for connection,
and a part to be supported integrally formed at a
peripheral edge of the functional part and fixed to the
peripheral edge about the anisotropically conductive film-
arranging hole in the frame plate,

10 wherein supposing that the shortest width of each of
the conductive parts for connection is W , and the number
average particle diameter of the conductive particles is D_n ,
a value of a ratio W/D_n of the shortest width of the
conductive part for connection to the number average
15 particle diameter of the conductive particles falls within
a range of 3 to 8, and a coefficient of variation of
particle diameter of the conductive particles is at most
50%,

wherein supposing that the weight average particle
20 diameter of the conductive particles is D_w , a value of a
ratio D_w/D_n of the weight average particle diameter to the
number average particle diameter is at most 5, and

wherein the number average particle diameter of the
conductive particles is 3 to 30 μm .

25 3. (Deleted)

4. (Deleted)

5. (Amended) The anisotropically conductive connector according to claim 2, wherein the conductive particles are those subjected to a classification treatment by an air classifier.

5 6. (Amended) The anisotropically conductive connector according to claim 2 or 5, wherein the conductive particles are those obtained by coating surfaces of core particles exhibiting magnetism with a high-conductive metal.

7. (Amended) The anisotropically conductive
10 connector according to any one of claims 2, 5 and 6, wherein the coefficient of linear thermal expansion of the frame plate is at most $3 \times 10^{-5}/K$.

8. (Amended) A conductive paste composition suitable for forming the elastic anisotropically conductive films in
15 the anisotropically conductive connector according to any one of claims 2 and 5 to 7, which comprises curable liquid silicone rubber and conductive particles exhibiting magnetism, wherein supposing that the shortest width of each of the conductive parts for connection in the elastic
20 anisotropically conductive film is W, and the number average particle diameter of the conductive particles is D_n , a value of a ratio W/D_n of the shortest width of the conductive part for connection to the number average particle diameter of the conductive particles falls within
25 a range of 3 to 8, and a coefficient of variation of particle diameter of the conductive particles is at most 50%.

9. (Amended) A probe member suitable for use in conducting electrical inspection of each of a plurality of integrated circuits formed on a wafer in a state of the wafer, which comprises:

5 a circuit board for inspection, on the surface of which inspection electrodes have been formed in accordance with a pattern corresponding to a pattern of electrodes to be inspected of the integrated circuits formed on the wafer, which is an object of inspection, and the anisotropically
10 conductive connector according to any one of claims 2 and 5 to 7, which is arranged on the surface of the circuit board for inspection.

10. The probe member according to claim 9, wherein the coefficient of linear thermal expansion of the frame
15 plate in the anisotropically conductive connector is at most $3 \times 10^{-5}/K$, and the coefficient of linear thermal expansion of a base material making up the circuit board for inspection is at most $3 \times 10^{-5}/K$.

11. The probe member according to claim 9 or 10,
20 wherein a sheet-like connector composed of an insulating sheet and a plurality of electrode structures each extending through in a thickness-wise direction of the insulating sheet and arranged in accordance with a pattern corresponding to the pattern of the electrodes to be
25 inspected is arranged on the anisotropically conductive connector.

12. A wafer inspection apparatus for conducting

electrical inspection of each of a plurality of integrated circuits formed on a wafer in a state of the wafer, which comprises the probe member according to any one of claims 9 to 11, wherein electrical connection to the integrated
5 circuits formed on the wafer, which is an object of inspection, is achieved through the probe member.

13. A wafer inspection method comprising electrically connecting each of a plurality of integrated circuits formed on a wafer to a tester through the probe
10 member according to any one of claims 9 to 11 to perform electrical inspection of the integrated circuits formed on the wafer.